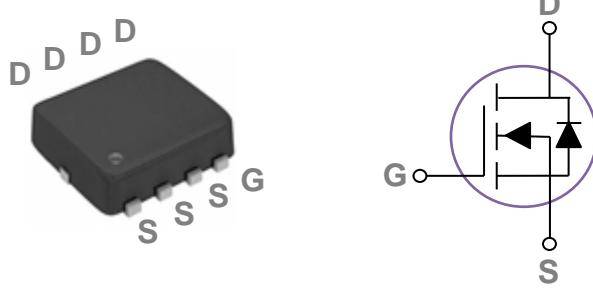


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### PPAK3X3 Pin Configuration



BVDSS	RDS(ON)	ID
100V	11.8mΩ	48A

### Features

- 100V,48A, RDS(ON) =11.8mΩ@VGS = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V <sub>Ds</sub>	Drain-Source Voltage	100	V
V <sub>Gs</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	48	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	30	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	192	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	115	mJ
I <sub>AS</sub>	Single Pulse Avalanche Current <sup>2</sup>	48	A
P <sub>D</sub>	Power Dissipation ( $T_c=25^\circ\text{C}$ )	61	W
	Power Dissipation – Derate above 25°C	0.49	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	2.04	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$\text{I}_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$\text{I}_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

**On Characteristics**

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	9.8	11.8	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=15\text{A}$	---	13	16.8	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
$\text{gfs}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=3\text{A}$	---	10	---	S

**Dynamic and switching Characteristics**

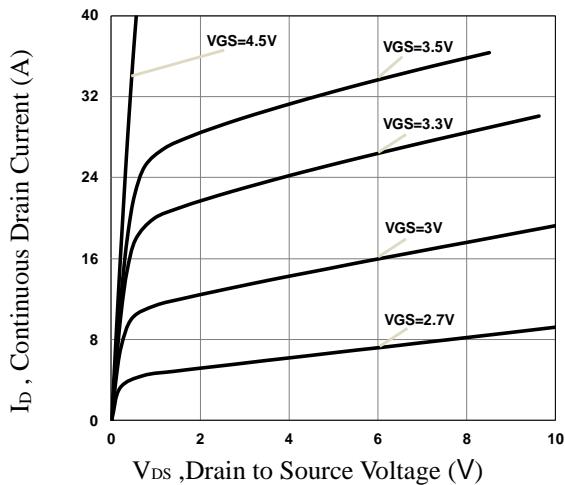
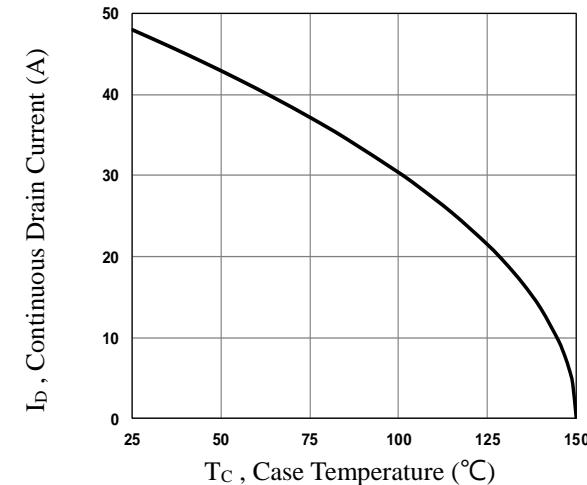
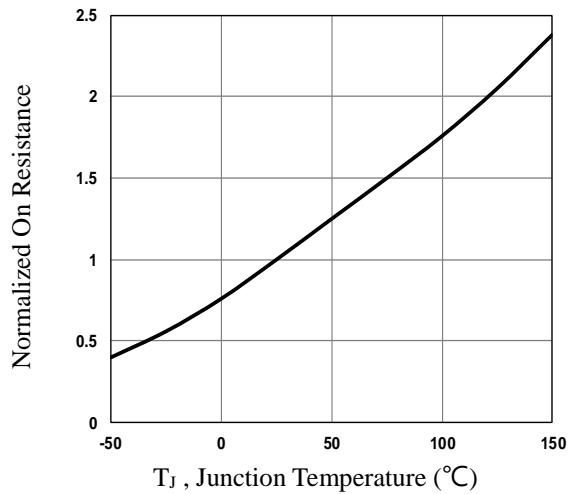
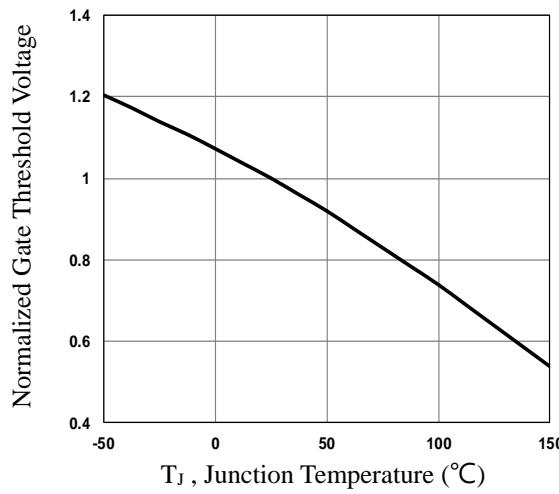
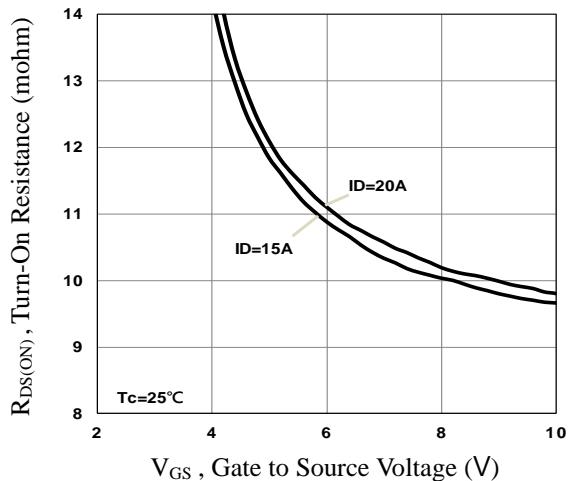
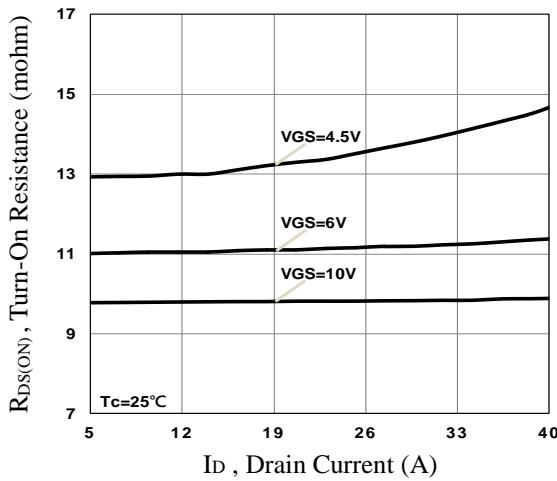
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=10\text{A}$	---	26.1	39	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	6.5	10	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	5.3	8	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$ $I_D=10\text{A}$	---	14.2	28	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	20.8	42	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	42	84	
$T_f$	Fall Time <sup>3, 4</sup>		---	30	60	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1450	2145	pF
$C_{\text{oss}}$	Output Capacitance		---	215	322	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	8	20	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.04	---	$\Omega$

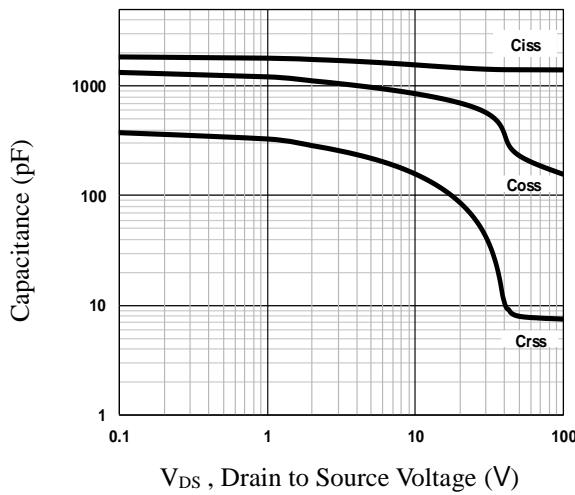
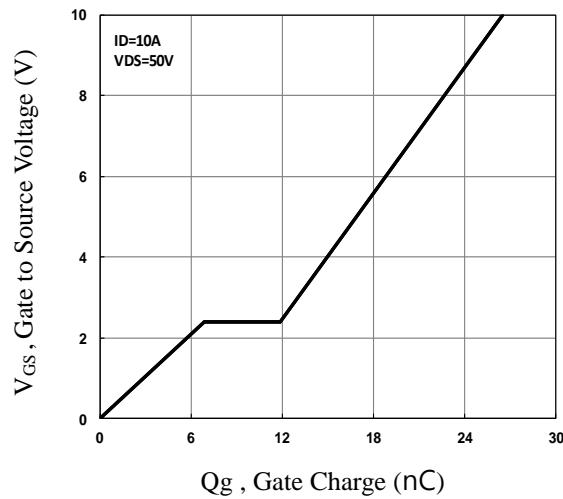
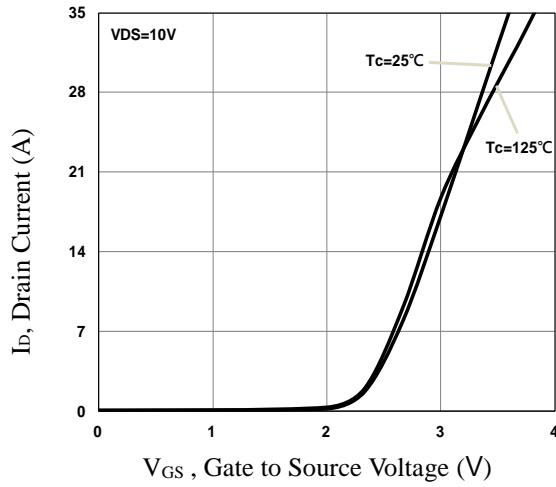
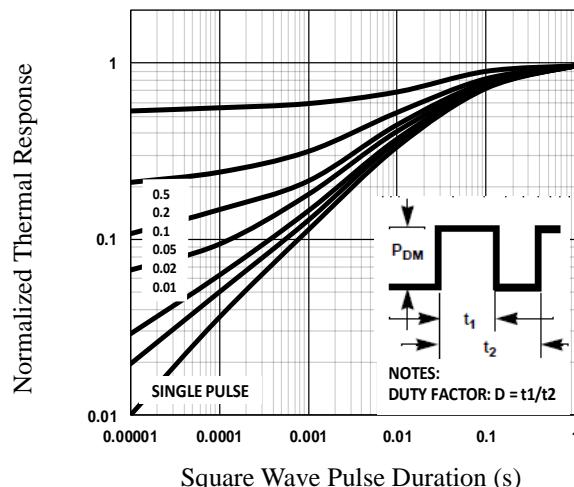
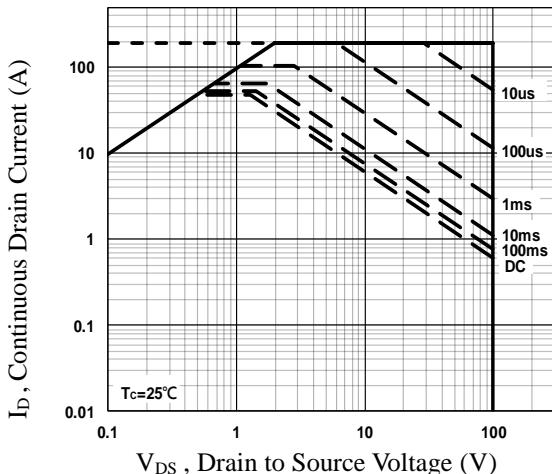
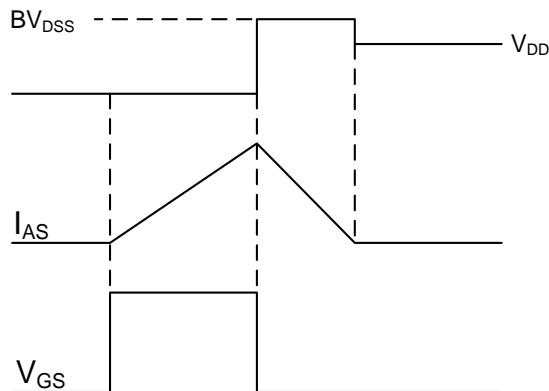
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	48	A
			---	---	96	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_R=100\text{V}$ , $I_s=10\text{A}$	---	155	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	230	---	nC

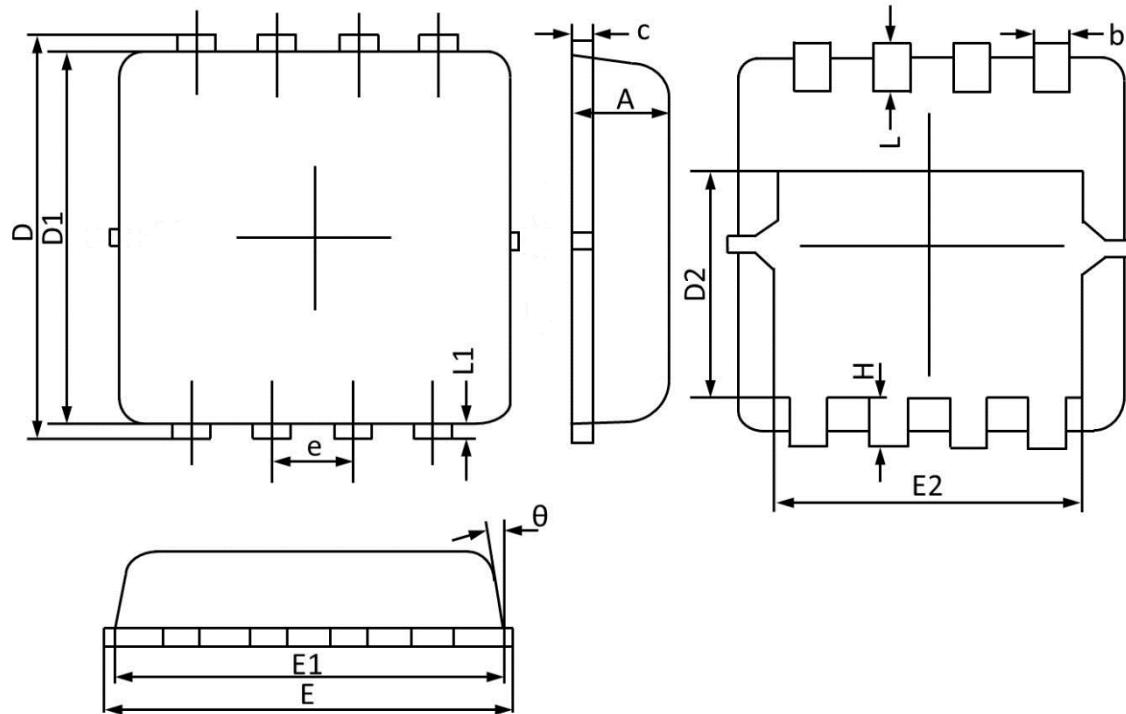
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=50\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=48\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Typical Output Characteristics**

**Fig.2 Continuous Drain Current vs.  $T_c$** 

**Fig.3 Normalized  $R_{DSON}$  vs.  $T_j$** 

**Fig.4 Normalized  $V_{th}$  vs.  $T_j$** 

**Fig.5 Turn-On Resistance vs.  $V_{GS}$** 

**Fig.6 Turn-On Resistance vs.  $I_D$**


**Fig.7 Capacitance Characteristics**

**Fig.8 Gate Charge Characteristics**

**Fig.9 Transfer Characteristics**

**Fig.10 Normalized Transient Impedance**

**Fig.11 Maximum Safe Operation Area**

**Fig.12 EAS Waveform**

## PPAK3x3 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°

## PPAK3X3 RECOMMENDED LAND PATTERN

